

Amendments to the Claims:

1. (Currently Amended) A substrate comprising
a metal plate, and
an insulating film, which is provided on the surface of the metal plate and which
~~includes~~ consists essentially of needle alumina particles and granular particles.
2. (Original) The substrate of claim 1, wherein the granular particles include at
least one of silica particles, MgO particles, and TiO₂ particles.
3. (Original) The substrate of claim 2, wherein the granular particles include silica
particles.
4. (Previously Presented) The substrate of claim 1, wherein the needle alumina
particles have an aspect ratio of 6 to 15.
5. (Original) The substrate of claim 4, wherein the needle alumina particles have a
major-axis length of 70 nm to 300 nm.
6. (Previously Presented) The substrate of claim 1, wherein the granular particles
have a mean particle size of 5 nm to 80 nm.
7. (Previously Presented) The substrate of claim 1, wherein the insulating film
includes 0.3 mass% to 80 mass% of the needle alumina particles.
8. (Previously Presented) The substrate of claim 1, wherein the insulating film has
a thickness of 0.3 μm to 3.5 μm .
9. (Previously Presented) The substrate of claim 1, wherein the insulating film has
a surface roughness of 0.3 μm or less.

10. (Previously Presented) The substrate of claim 1, wherein the metal plate is made of Cu, an Fe-Ni-Cr alloy, an Fe-Cr alloy, an Fe-Ni alloy, Fe or Al.

11. (Previously Presented) The substrate of claim 1, wherein the metal plate has a thickness of 0.05 mm to 0.5 mm.

12. (Withdrawn) A wiring board comprising
the substrate of claim 1, and
a wiring pattern that has been formed on the surface of the insulating film on the substrate.

13-21. (Canceled)